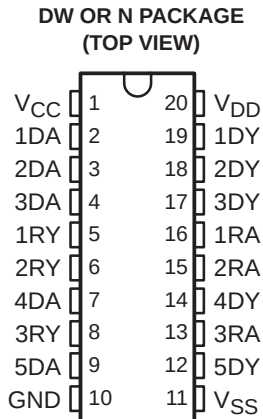


- **Single Chip With Easy Interface Between UART and Serial-Port Connector of an External Modem or Other Computer Peripheral**
- **Five Drivers and Three Receivers Meet or Exceed the Requirements of ANSI Standard TIA/EIA-232-F and ITU Recommendation V.28 Standards**
- **Supports Data Rates up to 120 kbit/s**
- **Complement to the GD75232**
- **Provides Pin-to-Pin Replacement for the Goldstar GD75323**
- **Pin-Out Compatible With SN75196**
- **Functional Replacement for the MC145405**



description

The GD75323 combines five drivers and three receivers from the trade-standard SN75188 and SN75189 bipolar quadruple drivers and receivers, respectively. The flow-through design of the GD75323 decreases the part count, reduces the board space required, and allows easy interconnection of the UART and serial-port connector. The all-bipolar circuits and processing of the GD75323 provide a rugged, low-cost solution for this function.

The GD75323 complies with the requirements of the ANSI TIA/EIA-232-F and ITU (formerly CCITT) V.28 standards. These standards are for data interchange between a host computer and a peripheral at signal rates up to 20 kbit/s. The switching speeds of the GD75323 are fast enough to support rates up to 120 kbit/s with lower capacitive loads (shorter cables). Interoperability at the higher signaling rates cannot be assured unless the designer has design control of the cable and the interface circuits at both ends. For interoperability at signaling rates up to 120 kbit/s, use of ANSI Standard TIA/EIA-423-B and TIA/EIA-422-B and ITU Recommendations V.10 and V.11 are recommended.

The GD75323 is characterized for operation over a temperature range of 0°C to 70°C.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

**TEXAS
INSTRUMENTS**

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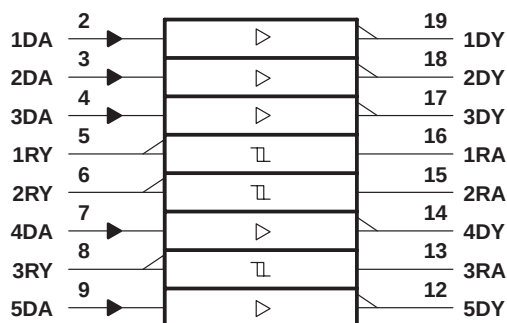
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GD75323

MULTIPLE RS-232 DRIVERS AND RECEIVERS

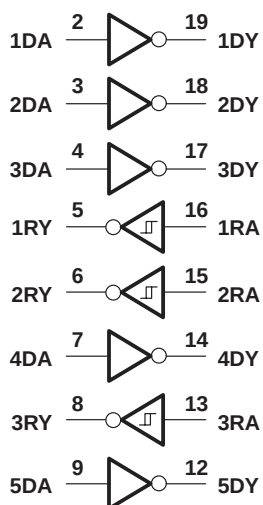
SLLS213A – JANUARY 1996 – REVISED JUNE 1999

logic symbol†

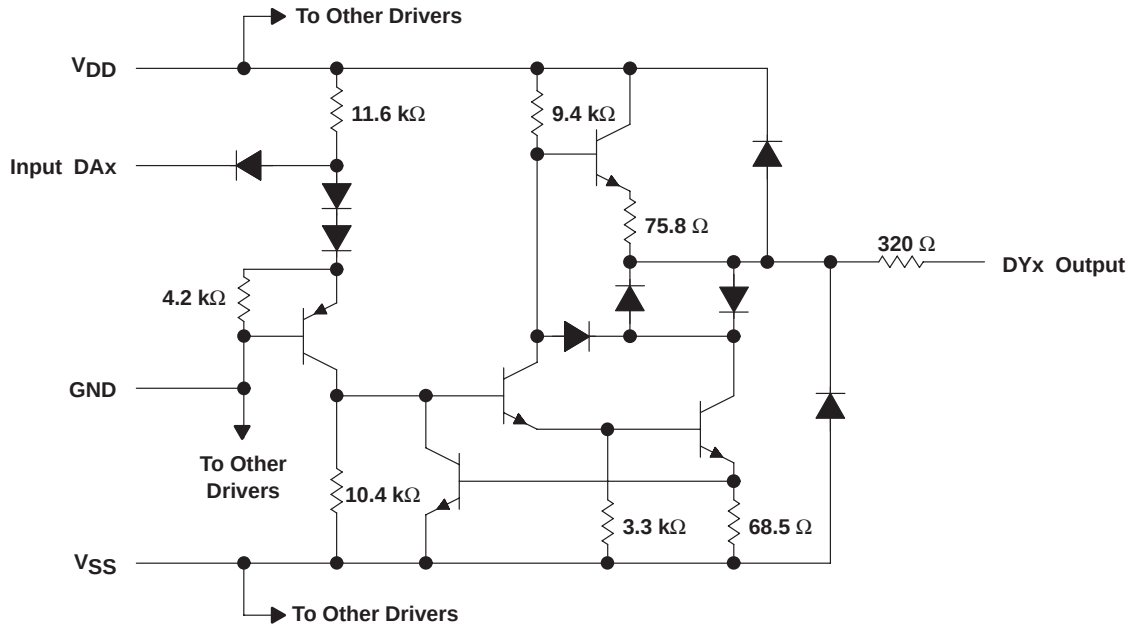


† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)

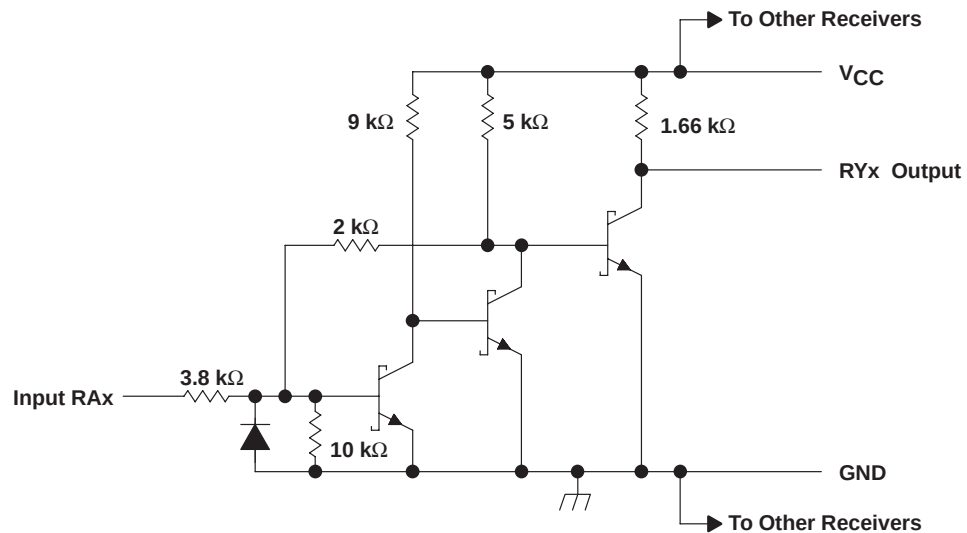


schematic (each driver)



Resistor values shown are nominal.

schematic (each receiver)



Resistor values shown are nominal.

GD75323

MULTIPLE RS-232 DRIVERS AND RECEIVERS

SLLS213A – JANUARY 1996 – REVISED JUNE 1999

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage, V_{CC} (see Note 1)	10 V
Supply voltage, V_{DD} (see Note 1)	15 V
Supply voltage, V_{SS} (see Note 1)	–15 V
Input voltage range, V_I : Driver	–15 V to 7 V
Receiver	–30 V to 30 V
Output voltage range, V_O (Driver)	–15 V to 15 V
Low-level output current, I_{OL} (Receiver)	20 mA
Package thermal impedance, θ_{JA} (see Note 2): DW package	97°C/W
N package	67°C/W
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	260°C
Storage temperature range, T_{stg}	–65°C to 150°C

[†] Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. All voltages are with respect to the network ground terminal.
2. The package thermal impedance is calculated in accordance with JESD 51, except for through-hole packages, which use a trace length of zero.

recommended operating conditions

		MIN	NOM	MAX	UNIT
Supply voltage	V_{DD}	7.5	9	13.5	V
	V_{SS}	–7.5	–9	–13.5	
	V_{CC}	4.5	5	5.5	
High-level input voltage, V_{IH}	Driver	1.9			V
Low-level input voltage, V_{IL}	Driver			0.8	V
High-level output current, I_{OH}	Driver			–6	mA
	Receiver			–0.5	
High-level output current, I_{OL}	Driver			6	mA
	Receiver			16	
Operating free-air temperature, T_A		0		70	°C

supply currents over operating free-air temperature range

PARAMETER	TEST CONDITIONS		MIN	MAX	UNIT
I_{DD} Supply current from V_{DD}	All inputs at 1.9 V, No load	$V_{DD} = 9\text{ V}, V_{SS} = -9\text{ V}$		25	mA
		$V_{DD} = 12\text{ V}, V_{SS} = -12\text{ V}$		32	
	All inputs at 0.8 V, No load	$V_{DD} = 9\text{ V}, V_{SS} = -9\text{ V}$		7.5	mA
		$V_{DD} = 12\text{ V}, V_{SS} = -12\text{ V}$		9.5	
I_{SS} Supply current from V_{SS}	All inputs at 1.9 V, No load	$V_{DD} = 9\text{ V}, V_{SS} = -9\text{ V}$		–25	mA
		$V_{DD} = 12\text{ V}, V_{SS} = -12\text{ V}$		–32	
	All inputs at 0.8 V, No load	$V_{DD} = 9\text{ V}, V_{SS} = -9\text{ V}$		–5.3	mA
		$V_{DD} = 12\text{ V}, V_{SS} = -12\text{ V}$		–5.3	
I_{CC} Supply current from V_{CC}	$V_{CC} = 5\text{ V},$	All inputs at 5 V, No load		20	mA



DRIVER SECTION

electrical characteristics over operating free-air temperature range, $V_{DD} = 9\text{ V}$, $V_{SS} = -9\text{ V}$, $V_{CC} = 5\text{ V}$ (unless otherwise noted)

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
V_{OH} High-level output voltage	$V_{IL} = 0.8\text{ V}$, $R_L = 3\text{ k}\Omega$, See Figure 1	6	7.5		V
V_{OL} Low-level output voltage (see Note 3)	$V_{IH} = 1.9\text{ V}$, $R_L = 3\text{ k}\Omega$, See Figure 1		-7.5	-6	V
I_{IH} High-level input current	$V_I = 5\text{ V}$, See Figure 2			10	μA
I_{IL} Low-level input current	$V_I = 0$, See Figure 2			-1.6	mA
$I_{OS(H)}$ High-level short-circuit output current (see Note 4)	$V_{IL} = 0.8\text{ V}$, $V_O = 0$, See Figure 1	-4.5	-9	-19.5	mA
$I_{OS(L)}$ Low-level short-circuit output current	$V_{IH} = 2\text{ V}$, $V_O = 0$, See Figure 1	4.5	9	19	mA
r_o Output resistance (see Note 5)	$V_{CC} = V_{DD} = V_{SS} = 0$, $V_O = -2\text{ V to } 2\text{ V}$	300			Ω

- NOTES: 3. The algebraic convention, where the more positive (less negative) limit is designated as maximum, is used in this data sheet for logic levels only, e.g., if -10 V is maximum, the typical value is a more negative voltage.
4. Output short-circuit conditions must maintain the total power dissipation below absolute maximum ratings.
5. Test conditions are those specified by TIA/EIA-232-F and as listed above.

switching characteristics, $V_{DD} = 12\text{ V}$, $V_{SS} = -12\text{ V}$, $V_{CC} = 5\text{ V} \pm 10\%$, $T_A = 25^\circ\text{C}$

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
t_{PLH} Propagation delay time, low- to high-level output	$R_L = 3\text{ k}\Omega$ to $7\text{ k}\Omega$, $C_L = 15\text{ pF}$, See Figure 3		315	500	ns
t_{PHL} Propagation delay time, high- to low-level output			75	175	ns
t_{TLH} Transition time, low- to high-level output	$R_L = 3\text{ k}\Omega$ to $7\text{ k}\Omega$, $C_L = 15\text{ pF}$, See Figure 3		60	100	ns
	$R_L = 3\text{ k}\Omega$ to $7\text{ k}\Omega$, $C_L = 2500\text{ pF}$, See Figure 3 and Note 6		1.7	2.5	μs
t_{THL} Transition time, high- to low-level output (see Note 5)	$R_L = 3\text{ k}\Omega$ to $7\text{ k}\Omega$, $C_L = 15\text{ pF}$, See Figure 3		40	75	ns
	$R_L = 3\text{ k}\Omega$ to $7\text{ k}\Omega$, $C_L = 2500\text{ pF}$, See Figure 3 and Note 7		1.5	2.5	μs

- NOTES: 6. Measured between -3 V and 3 V points of the output waveform (TIA/EIA-232-F conditions), all unused inputs are tied either high or low.
7. Measured between 3 V and -3 V points of the output waveform (TIA/EIA-232-F conditions), all unused inputs are tied either high or low.

GD75323

MULTIPLE RS-232 DRIVERS AND RECEIVERS

SLLS213A – JANUARY 1996 – REVISED JUNE 1999

RECEIVER SECTION

electrical characteristics over recommended operating conditions (unless otherwise noted)

PARAMETER		TEST CONDITIONS		MIN	TYP†	MAX	UNIT
V _{IT+}	Positive-going input threshold voltage	See Figure 5	T _A = 25°C	1.75	1.9	2.3	V
			T _A = 0°C to 70 °C	1.55		2.3	
V _{IT–}	Negative-going input threshold voltage	See Figure 5		0.75	0.97	1.25	
V _{hys}	Input hysteresis voltage (V _{IT+} – V _{IT–})			0.5			
V _{OH}	High-level output voltage	I _{OH} = –0.5 mA	V _{IH} = 0.75 V	2.6	4	5	V
			Inputs open	2.6			
V _{OL}	Low-level output voltage	I _{OL} = 10 mA, V _I = 3 V			0.2	0.45	V
I _{IH}	High-level input current	V _I = 25 V, See Figure 5		3.6		8.3	mA
		V _I = 3 V, See Figure 5		0.43			
I _{IL}	Low-level input current	V _I = –25 V, See Figure 5		–3.6		–8.3	mA
		V _I = –3 V, See Figure 5		–0.43			
I _{OS}	Short-circuit output current	See Figure 4			–3.4	–12	mA

† All typical values are at T_A = 25°C, V_{CC} = 5 V, V_{DD} = 9 V, and V_{SS} = –9 V.

switching characteristics, V_{CC} = 5 V, V_{DD} = 12 V, V_{SS} = –12 V, T_A = 25°C

PARAMETER		TEST CONDITIONS		MIN	TYP	MAX	UNIT
t _{PLH}	Propagation delay time, low- to high-level output	C _L = 50 pF, R _L = 5 kΩ, See Figure 6			107	500	ns
t _{PHL}	Propagation delay time, high- to low-level output				42	150	ns
t _{TLH}	Transition time, low- to high-level output				175	525	ns
t _{THL}	Transition time, high- to low-level output				16	60	ns

PARAMETER MEASUREMENT INFORMATION

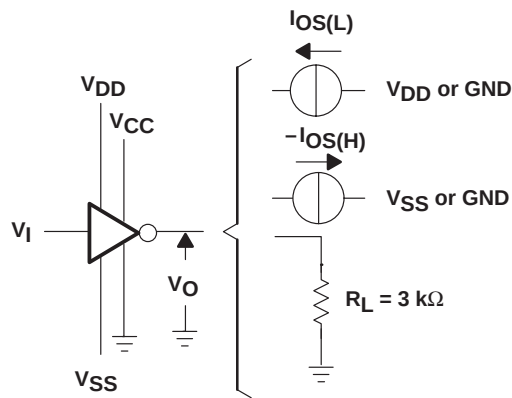


Figure 1. Driver Test Circuit for V_{OH}, V_{OL}, I_{OS(H)}, and I_{OS(L)}

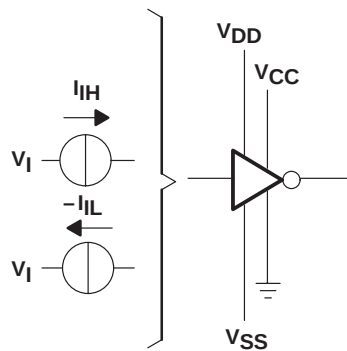
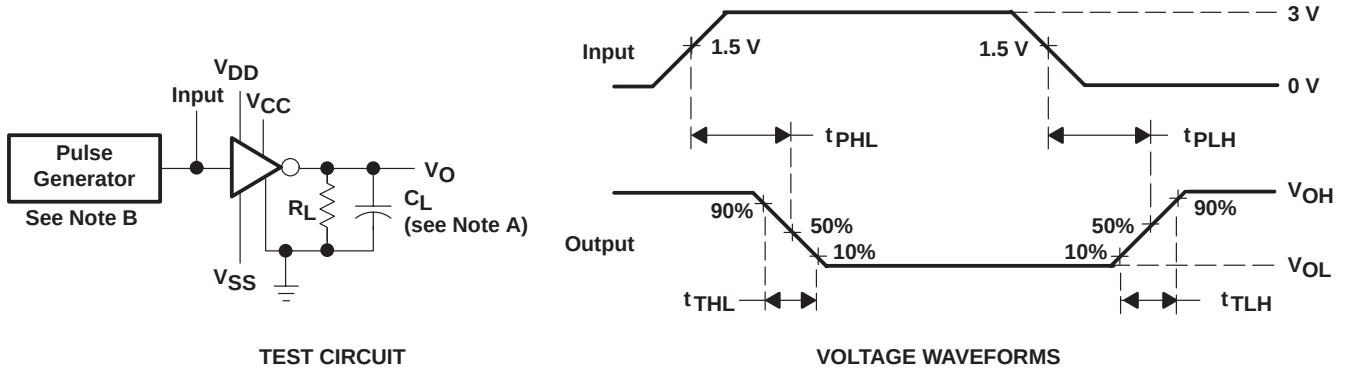


Figure 2. Driver Test Circuit for I_{IH} and I_{IL}

PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.
B. The pulse generator has the following characteristics: $t_W = 25 \mu s$, $PRR = 20 \text{ kHz}$, $Z_O = 50 \Omega$, $t_r = t_f < 50 \text{ ns}$.

Figure 3. Driver Test Circuit and Voltage Waveforms

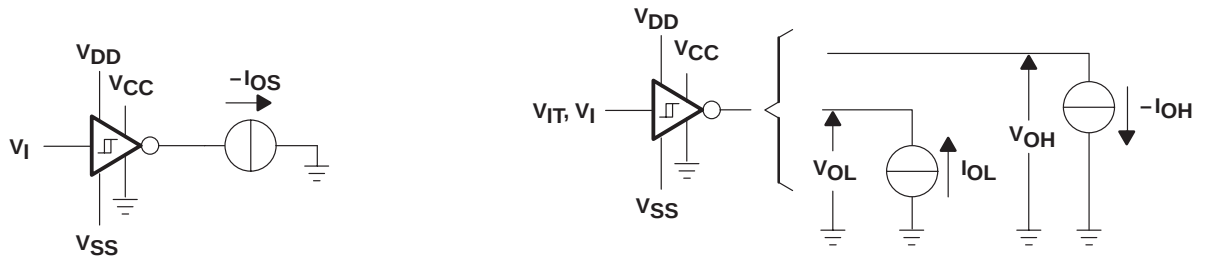
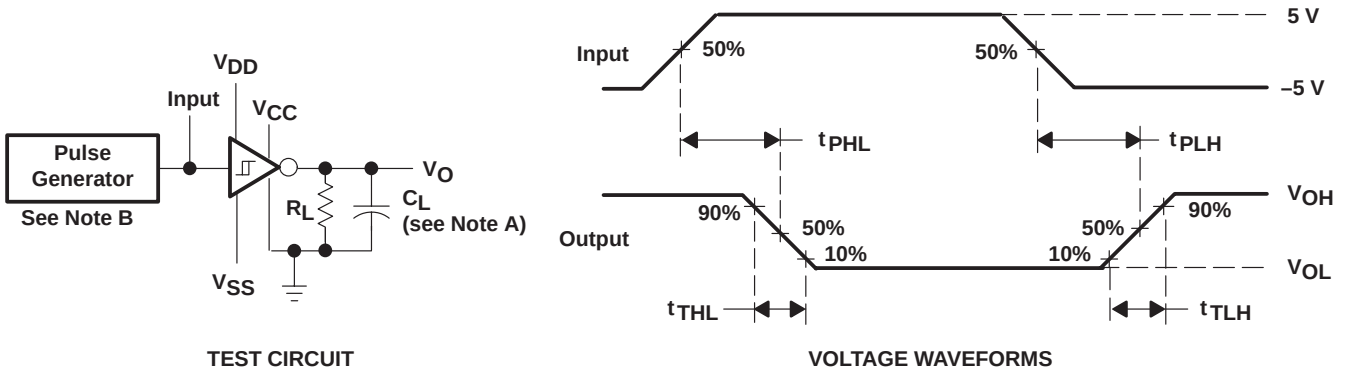


Figure 4. Receiver Test Circuit for I_{OS}

Figure 5. Receiver Test Circuit for V_{IT} , V_{OH} , and V_{OL}



NOTES: A. C_L includes probe and jig capacitance.
B. The pulse generator has the following characteristics: $t_W = 25 \mu s$, $PRR = 20 \text{ kHz}$, $Z_O = 50 \Omega$, $t_r = t_f < 50 \text{ ns}$.

Figure 6. Receiver Propagation and Transition Times

TYPICAL CHARACTERISTICS

DRIVER SECTION

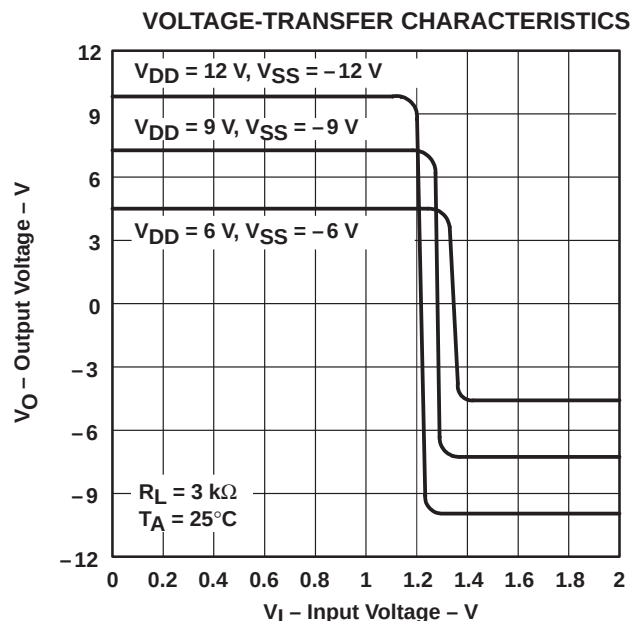


Figure 7

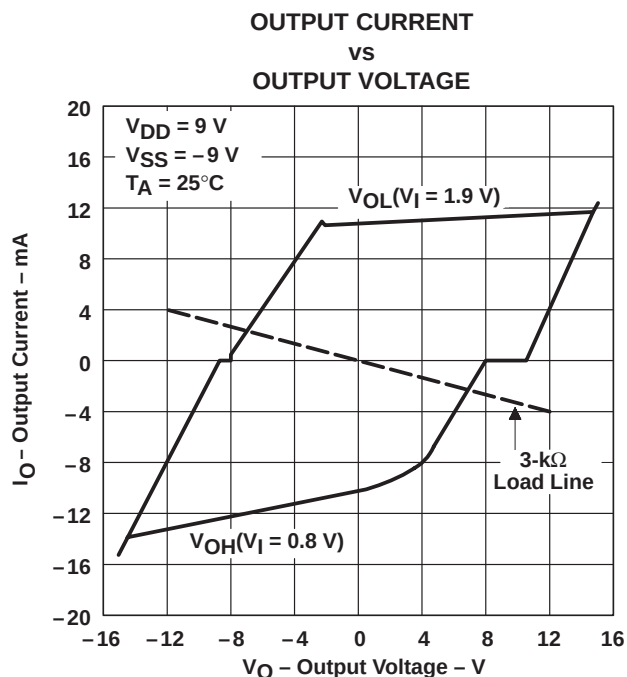


Figure 8

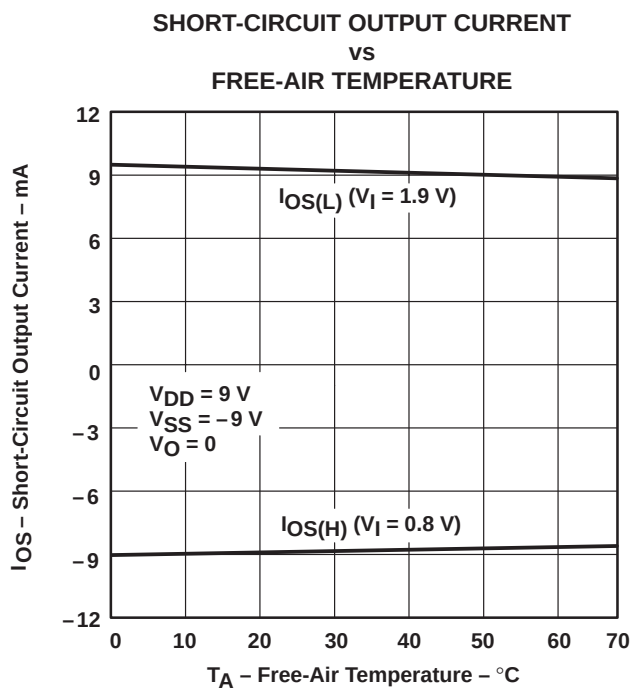


Figure 9

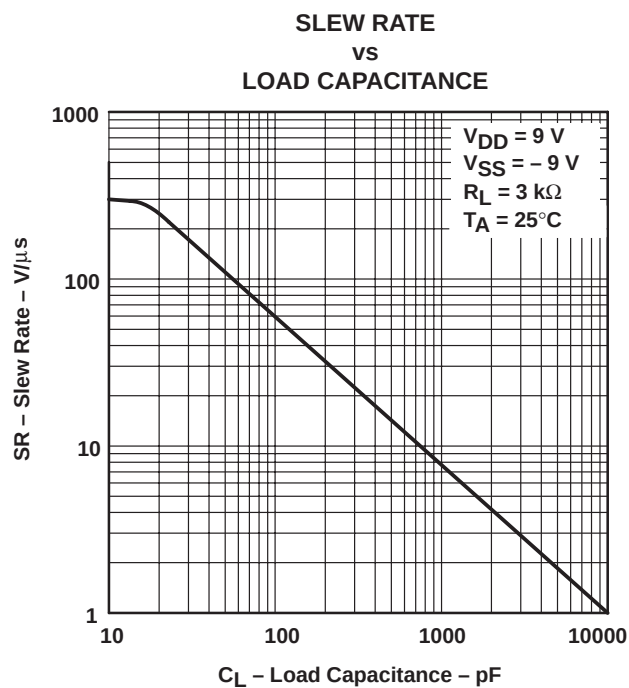


Figure 10

TYPICAL CHARACTERISTICS
RECEIVER SECTION

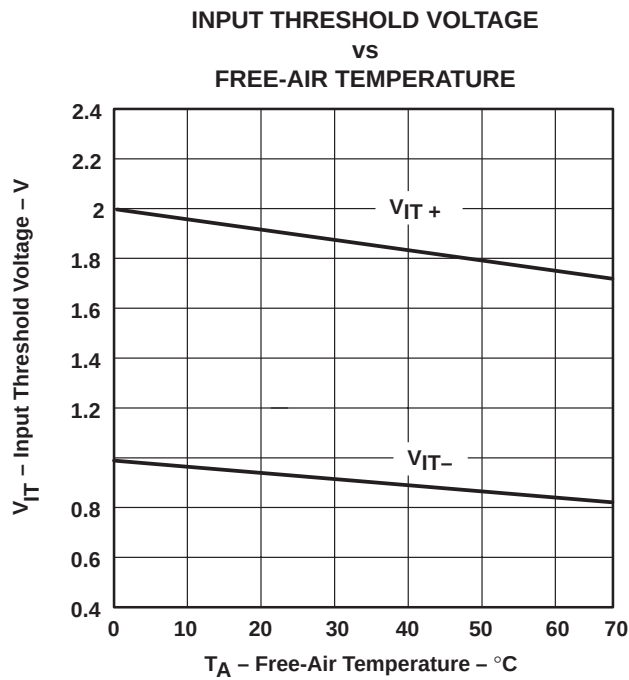


Figure 11

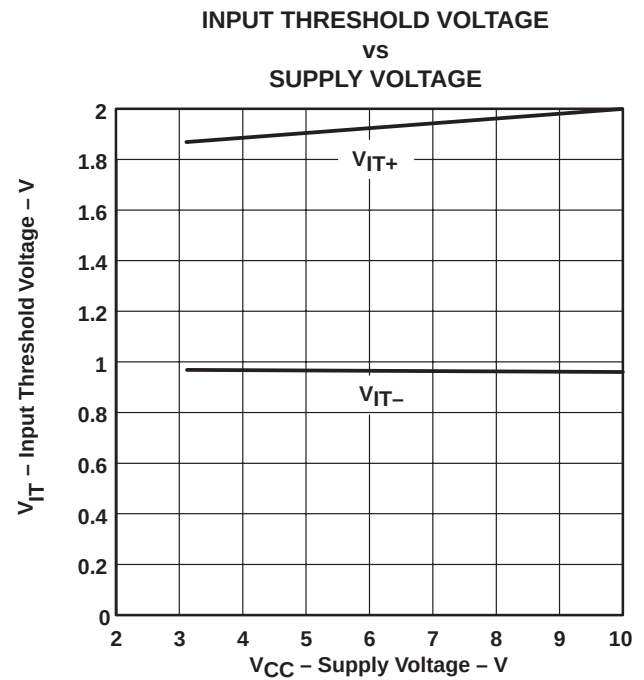
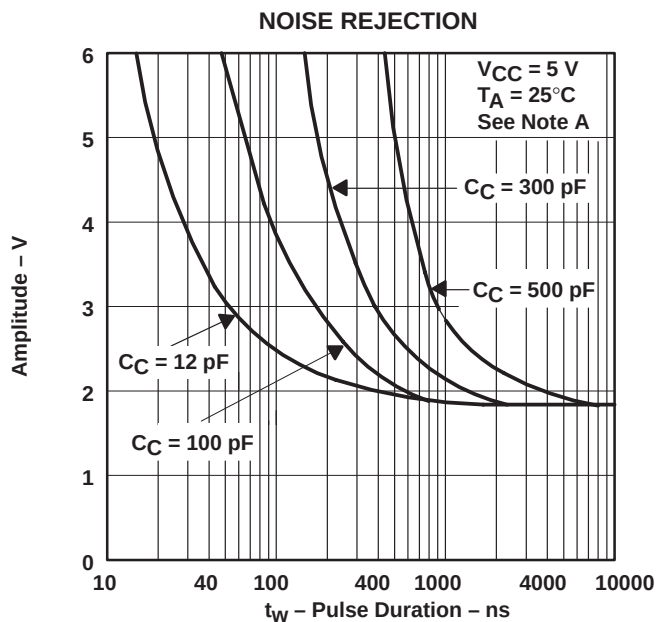


Figure 12



NOTE A: This figure shows the maximum amplitude of a positive-going pulse that, starting from 0 V, does not cause a change of the output level.

Figure 13

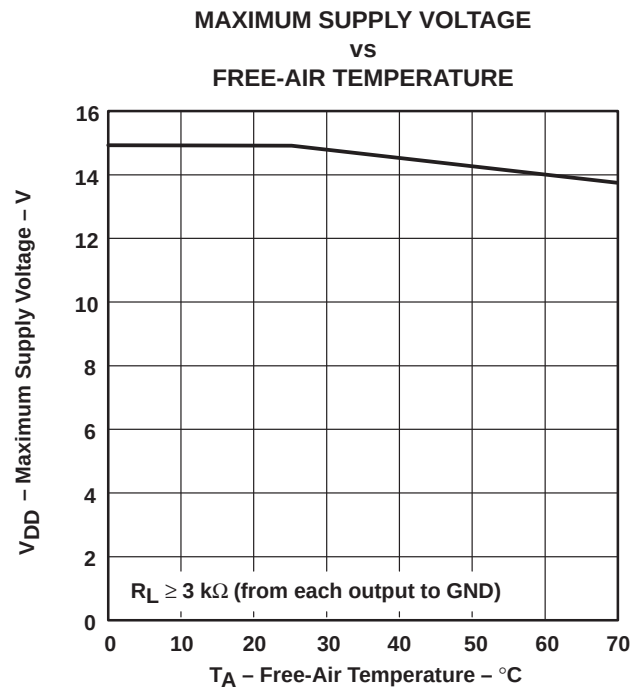


Figure 14

GD75323

MULTIPLE RS-232 DRIVERS AND RECEIVERS

SLLS213A – JANUARY 1996 – REVISED JUNE 1999

APPLICATION INFORMATION

Diodes placed in series with the V_{DD} and V_{SS} leads protect the GD75323 in the fault condition in which the device outputs are shorted to V_{DD} or V_{SS} , and the power supplies are at low and provide low-impedance paths to ground (see Figure 15).

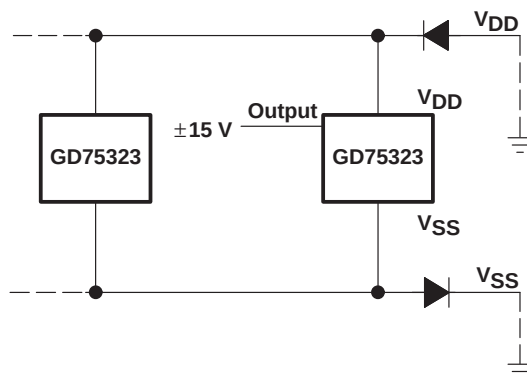
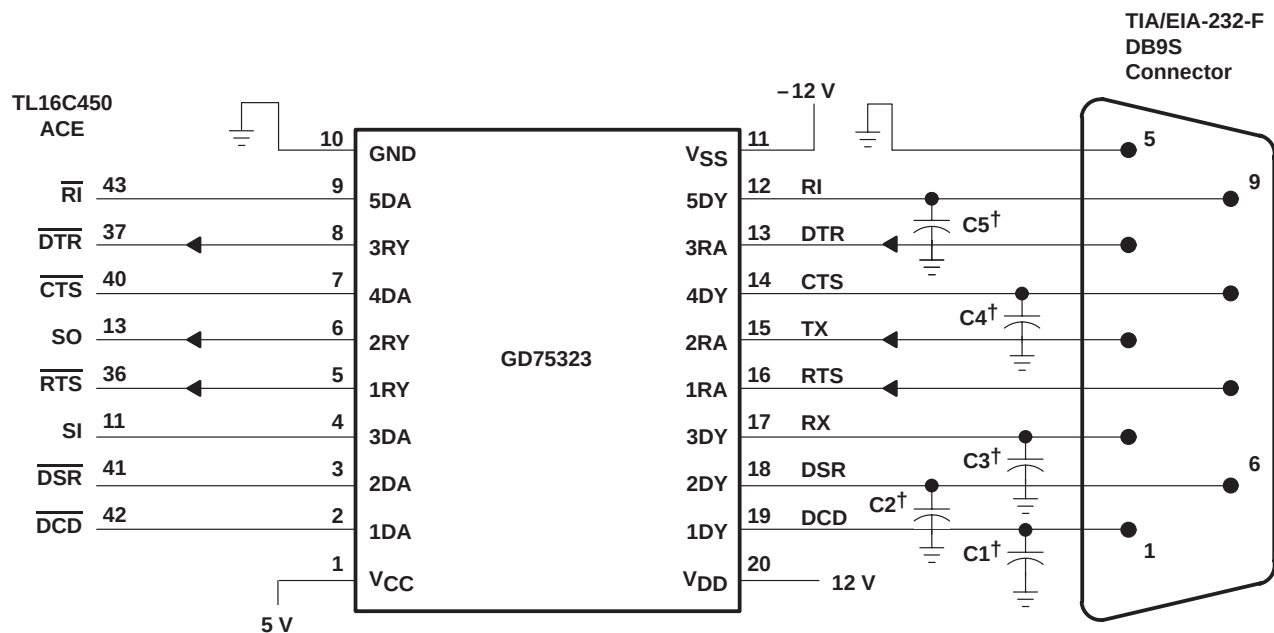


Figure 15. Power-Supply Protection to Meet Power-Off Fault Conditions of TIA/EIA-232-F



† See Figure 10 to select the correct values for the loading capacitors (C1, C2, C3, C4, and C5), which may be required to meet the RS-232 maximum slew-rate requirement of 30 V/μs. The value of the loading capacitors required depends upon the line length and desired slew rate, but is typically 330 pF.

NOTE C: To use the receivers only, V_{DD} and V_{SS} both must be powered or tied to ground.

Figure 16. Typical Connection

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
GD75323DW	Active	Production	SOIC (DW) 20	25 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	GD75323
GD75323DW.A	Active	Production	SOIC (DW) 20	25 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	GD75323
GD75323DWR	Active	Production	SOIC (DW) 20	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	GD75323
GD75323DWR.A	Active	Production	SOIC (DW) 20	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	GD75323

⁽¹⁾ **Status:** For more details on status, see our [product life cycle](#).

⁽²⁾ **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

⁽⁴⁾ **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

⁽⁵⁾ **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

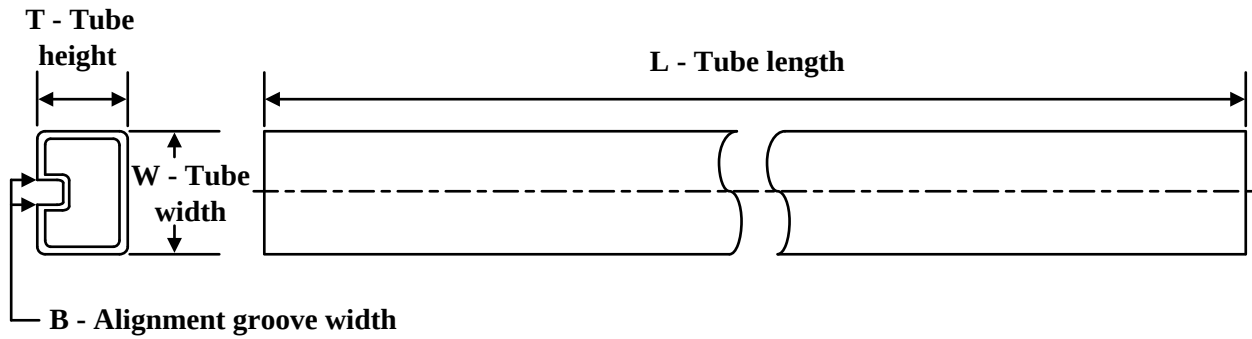
⁽⁶⁾ **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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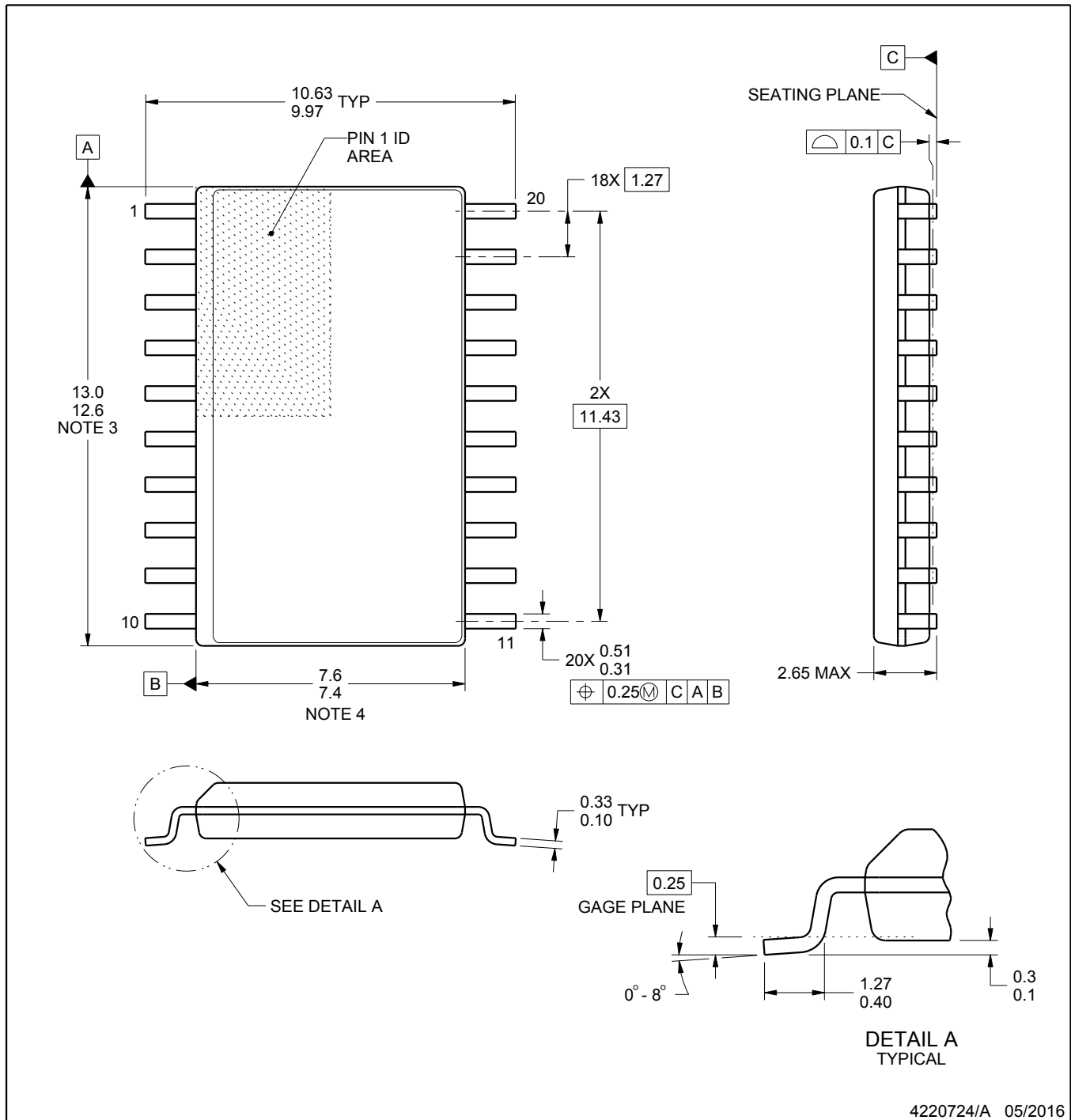
In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

TUBE



*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (μm)	B (mm)
GD75323DW	DW	SOIC	20	25	507	12.83	5080	6.6
GD75323DW	DW	SOIC	20	25	506.98	12.7	4826	6.6
GD75323DW.A	DW	SOIC	20	25	507	12.83	5080	6.6
GD75323DW.A	DW	SOIC	20	25	506.98	12.7	4826	6.6



4220724/A 05/2016

NOTES:

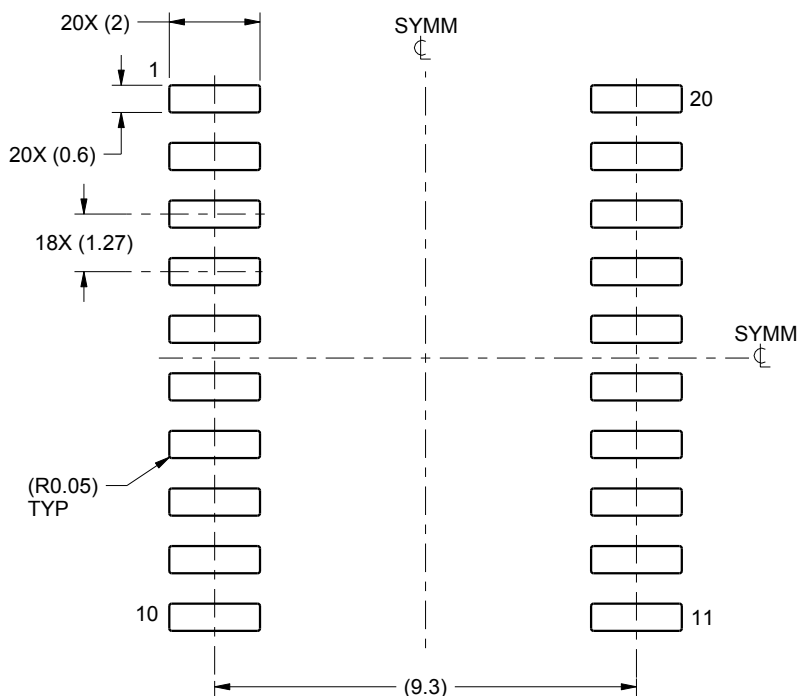
1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm per side.
5. Reference JEDEC registration MS-013.

EXAMPLE BOARD LAYOUT

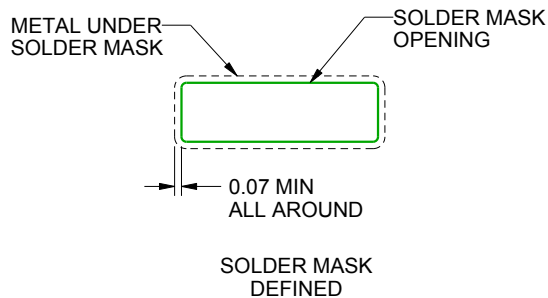
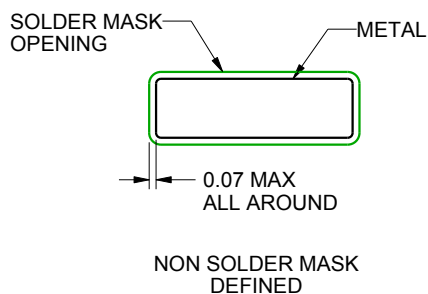
DW0020A

SOIC - 2.65 mm max height

SOIC



LAND PATTERN EXAMPLE
SCALE:6X



SOLDER MASK DETAILS

4220724/A 05/2016

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

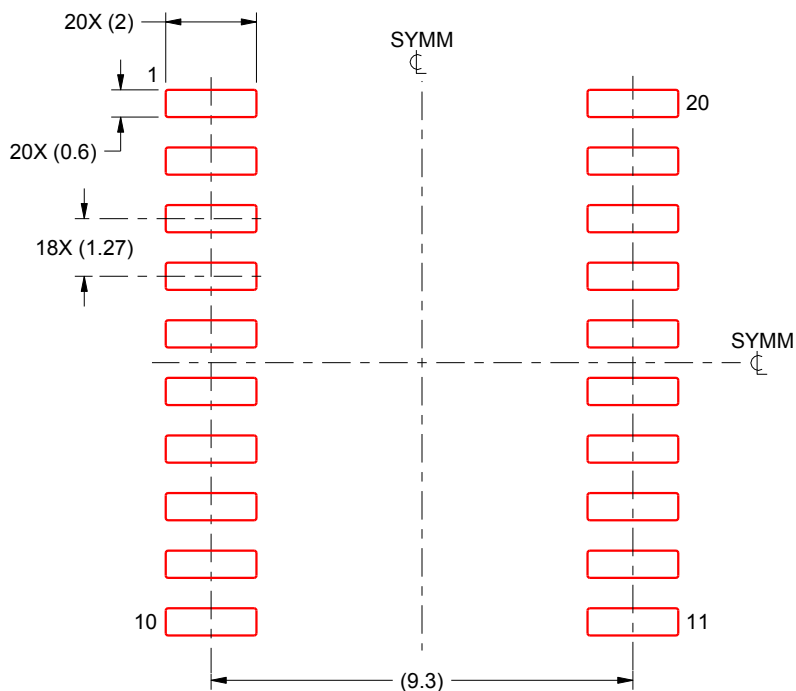
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

DW0020A

SOIC - 2.65 mm max height

SOIC



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:6X

4220724/A 05/2016

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

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